innodisk

M.2 (P80) 4IE3 Series Ultra iSLC

Customer:	Customer:
Customer	Customer
Part	Part
Number:	Number:
Innodisk	Innodisk
Part	Part
Number:	Number:
Innodisk	Innodisk
Model Name:	Model Name
Date:	Date:

Innodisk	Customer
Approver	Approver

Total Solution For Industrial Flash Storage



Features:

- PCIe Gen 4 x4, NVMe SSD
- Kioxia 3D TLC NAND
- M.2 Type 2280-D2-M
- Standard/Wide-temperature
- iPowerguard
- iDataguard
- Dynamic Thermal Management
- 256 bit AES hardware based encryption
- Support Ultra iSLC technology
- Support Write Protection (optional)
- Support TCG OPAL function (optional)

Performance:

- Sequential Read up to 3,700 MB/s
- Sequential Write up to 3,200 MB/s

Power Requirements:

Input Voltage:	3.3V± 5%
Max Operating Wattage (R/W):	4.7W
Idle Wattage:	1.0W

Reliability:

Capacity	TBW (Client)	DWPD
40GB	1,911	28.78
80GB	3,822	28.78
160GB	8,624	32.47
320GB	17,081	32.15
640GB	39,424	37.10

Data Retention	1 Year
Warranty	5 Years

1 year data retention is at NAND life end.

For warranty details, please refer to:

https://www.innodisk.com/en/support_and_service/warranty

V1.2

innodisk

Table of contents

1. PRODUCT OVERVIEW	8
1.1 INTRODUCTION OF INNODISK M.2 (P80) 4IE3	8
1.2 Product View and Models	8
1.3 PCIe Interface	9
2. PRODUCT SPECIFICATIONS	.10
2.1 CAPACITY AND DEVICE PARAMETERS	10
2.2 PERFORMANCE	10
2.3 ELECTRICAL SPECIFICATIONS	-
2.3.1 Power Requirement	
2.3.2 Power Consumption	
2.4 ENVIRONMENTAL SPECIFICATIONS	
2.4.1 Temperature Ranges	
2.4.2 Humidity	
2.4.3 Shock and Vibration	. 11
2.4.4 Mean Time between Failures (MTBF)	.12
2.5 CE AND FCC COMPATIBILITY	12
2.6 ROHS COMPLIANCE	12
2.7 RELIABILITY	13
2.8 TRANSFER MODE	13
2.9 PIN ASSIGNMENT	14
2.10 MECHANICAL DIMENSIONS	16
2.11 ASSEMBLY WEIGHT	17
2.12 Seek Тіме	17
2.13 NAND FLASH MEMORY	17
3. THEORY OF OPERATION	.18
3.1 OVERVIEW	18
3.2 PCIE GEN 4 x4 CONTROLLER	18
3.3 Error Detection and Correction	18
3.4 WEAR-LEVELING	19
3.5 BAD BLOCKS MANAGEMENT	19
3.6 GARBAGE COLLECTION/TRIM	19
3.7 End to End Data Path Protection	19
3.8 THERMAL MANAGEMENT	19
3.9 IDATAGUARD	19
3.10 THERMAL THROTTLING	20
3.11 TCG OPAL (OPTIONAL)	20
4. INSTALLATION REQUIREMENTS	.21

4.1 M.2 (P80) 4IE3 PIN DIRECTIONS	21
4.2 ELECTRICAL CONNECTIONS FOR M.2 (P80) 4IE3	21
4.3 DEVICE DRIVE	21
5. SMART / HEALTH INFORMATION	22
5.1 GET LOG PAGE (LOG IDENTIFIER 02H)	22
6. PART NUMBER RULE	27

REVISION HISTORY

Revision	Description	Date
V1.0	First Release	May., 2024
V1.1	Update Transfer Mode	Sep., 2024
	Update Data Retention information	
V1.2	Update Performance Test	May., 2025

List of Tables

TABLE 1: DEVICE PARAMETERS	10
TABLE 2: PERFORMANCE- 112 LAYERS 3D TLC	10
TABLE 3: INNODISK M.2 (P80) 4IE3 POWER REQUIREMENT	11
TABLE 4: POWER CONSUMPTION	11
TABLE 5: TEMPERATURE RANGE FOR M.2 (P80) 4IE3	11
TABLE 6: SHOCK/VIBRATION TESTING FOR M.2 (P80) 4IE3	11
TABLE 7: M.2 (P80) 4IE3 MTBF	12
TABLE 8: M.2 (P80) 4IE3 ESD	12
TABLE 9: M.2 (P80) 4IE3 TBW	13
TABLE 10: INNODISK M.2 (P80) 4IE3 PIN ASSIGNMENT	14
TABLE 11: GET LOG PAGE – SMART / HEALTH INFORMATION LOG	22

List of Figures

FIGURE 1: INNODISK M.2 (P80) 4IE3 (STANDARD-TEMPERATURE)	8
FIGURE 2: INNODISK M.2 (P80) 4IE3 (WIDE-TEMPERATURE)	8
FIGURE 3: INNODISK M.2 (P80) 4IE3 MECHANICAL DRAWING	16
FIGURE 4: INNODISK M.2 (P80) 4IE3 WITH HEATSINK	16
FIGURE 5: INNODISK M.2 (P80) 4IE3 BLOCK DIAGRAM	
FIGURE 6: SIGNAL SEGMENT AND POWER SEGMENT	21

1. Product Overview

1.1 Introduction of Innodisk M.2 (P80) 4IE3

Innodisk M.2 (P80) 4IE3 is Ultra iSLC series which is designed to outdo the endurance, performance and reliability of 3D TLC-based solutions. Through the use of flash management algorithms, Ultra iSLC improves SSD endurance up to 100,000 times. In addition, Ultra iSLC improves the performance of solid state drives, with similar write performance of SLC-based solutions.

M.2 (P80) 4IE3 supports PCIe Gen 4x4, and it is compliant with NVMe 1.4 providing excellent performance. M.2 (P80) 4IE3 with heat-spreading design dissipate heat generating from IC making SSD perform more steady. M.2 (P80) 4IE3 have Die RAID protection to reduce bad blocks happening and optimize data integrity.

Innodisk M.2 (P80) 4IE3 is designed with AES engine, which is a built in controller. When controller receives the data package from host, AES engine encrypts the data package and saves the encrypted data into NAND flash. Thus, unauthorized personal has no access to decrypt the data in NAND flash.

1.2 Product View and Models

Innodisk M.2 (P80) 4IE3 is available in follow capacities with industrial 3D TLC flash ICs.

M.2 (P80) 4IE3 40GB
M.2 (P80) 4IE3 80GB
M.2 (P80) 4IE3 160GB
M.2 (P80) 4IE3 320GB
M.2 (P80) 4IE3 640GB



Figure 1: Innodisk M.2 (P80) 4IE3 (Standard-temperature)



Figure 2: Innodisk M.2 (P80) 4IE3 (Wide-temperature)

(Note. For write protection function, please contact sales for customization)

1.3 PCIe Interface

Innodisk M.2 (P80) 4IE3 supports PCIe Gen 4 interface and compliant with NVMe 1.4. M.2 (P80) 4IE3 can work under PCIe Gen 1, Gen 2 and Gen 3.

Most of operating system includes NVMe in-box driver now. For more information about the driver support in each OS, please visit <u>https://nvmexpress.org/drivers/</u>.



2. Product Specifications

2.1 Capacity and Device Parameters

M.2 (P80) 4IE3 device parameters are shown in Table 1.

Capacity	Cylinders	Heads	Sectors	LBA	User	
Capacity	Cymders	neaus	Sectors	Sectors LDA	LDA	Capacity(MB)
40GB	16383 16			78161328	38164	
80GB				156301488	76319	
160GB		16	63	312581808	152627	
320GB				625142448	305245	
640GB			1250263728	610480		

Table 1: Device parameters

2.2 Performance

Burst Transfer Rate: 8 GB/s

Table 2: Perfor	mance- 112	Layers 3	3D TLC
-----------------	------------	----------	--------

Capacity	Unit	40GB	80GB	160GB	320GB	640GB
Sequential*		1 450	2 000	2 650	2 650	2 700
Read (Q8T1)	MD /a	1,450	2,900	3,650	3,650	3,700
Sequential*	MB/s	960	1 (50	2 900	2 1 0 0	2 200
Write (Q8T1)		860	1,650	2,800	3,100	3,200
4KB Random**		F 4 000	108 000	424.000	C21 000	C 4 2 000
Read (Q32T16)	TOPC	54,000	108,000	434,000	631,000	642,000
4KB Random**	IOPS	205 000	250.000	F00 000	C 4 8 000	COE 000
Write (Q32T16)		205,000	359,000	599,000	648,000	605,000

Note: * Performance results are 4IE3 with Kioxia BiCS5 NAND composition measured in Room Temperature with Out-of-Box devices and may vary depending on overall system setup.

Note: ** Performance results are based on CrystalDiskMark 8.0.1 with file size 1000MB. Unit of 4KB item is IOPS.

2.3 Electrical Specifications

2.3.1 Power Requirement

Table 3: Innodisk M.2 (P80) 4IE3 Power Requirement

Item	Symbol	Rating	Unit
Input voltage	VIN	+3.3 DC +- 5%	V

2.3.2 Power Consumption

Tab	le 4:	Power	Consumption	
		Г		

Mode	Power Consumption (W)
Read	4.5
Write	4.7
Idle	1.0
Power on peak	4.2

Target: 640GB M.2 (P80) 4IE3

Note: Current results may vary depending on system components and power circuit

design. Please refer to the test report for other capacities.

2.4 Environmental Specifications

2.4.1 Temperature Ranges

Table 5: Temperature range for M.2 (P80) 4IE3

Temperature	Range
Operating	Standard Grade: 0°C to +70°C
	Industrial Grade: -40°C to +85°C
Storage	-40°C to +85°C

2.4.2 Humidity

Relative Humidity: 10-95%, non-condensing

2.4.3 Shock and Vibration

Table 6: Shock/Vibration Testing for M.2 (P80) 4IE3

Reliability	Test Conditions	Reference Standards
Vibration	7 Hz to 2K Hz, 20G, 3 axes	IEC 60068-2-6
Mechanical Shock	Duration: 0.5ms, 1500 G, 3 axes	IEC 60068-2-27



2.4.4 Mean Time between Failures (MTBF)

Table 7 summarizes the MTBF prediction results for various M.2 (P80) 4IE3 configurations. The analysis was performed using a RAM Commander[™] failure rate prediction.

- **Failure Rate**: The total number of failures within an item population, divided by the total number of life units expended by that population, during a particular measurement interval under stated condition.
- **Mean Time between Failures (MTBF)**: A basic measure of reliability for repairable items: The mean number of life units during which all parts of the item perform within their specified limits, during a particular measurement interval under stated conditions.

Table 7: M.2 (P80) 4IE3 MTBF

Product	Condition	MTBF (Hours)	
Innodisk M.2 (P80) 4IE3	Telcordia SR-332 GB, 25°C	>3,000,000	

2.5 CE and FCC Compatibility

M.2 (P80) 4IE3 conforms to CE and FCC requirements.

Table 8: M.2 (P80) 4IE3 ESD

Reliability	Reference standards
Electrostatic Discharge (ESD)	IEC 61000-4-2 ESD

2.6 RoHS Compliance

M.2 (P80) 4IE3 is fully compliant with RoHS directive.



2.7 Reliability

Table 9: M.2 (P80) 4IE3 TBW

Parameter	Valu	Value			
Read Cycles	Unlin	Unlimited Read Cycles			
Flash endurance	100,0	000 P/E cycles			
Error Correct Code	Supp	ort(LDPC)			
Data Retention	Unde	Under 40°C:			
	1 Yea	1 Year at NAND Life End			
TBW* (Total Bytes	s Writt	t en) Unit: TB			
Capacity		Sequential workload Client workload			
40GB		3,551	1,911		
80GB		7,102 3,822			
160GB		14,204 8,624			
320GB		28,409 17,081			
640GB		56,818	39,424		
		·			

* Note:

1. Sequential: Mainly sequential write are estimated by PassMark Burnin Test v8.1 pro.

2. Client: Follow JESD218 Test method and JESD219A Workload, tested by ULINK.

3. Client workload lower than 64GB is not specified in JEDEC219A.

4. Based on out-of-box performance.

2.8 Transfer Mode

M.2 (P80) 4IE3 support following transfer mode:

PCIe Gen 4: 8GB/s

PCIe Gen 3: 4GB/s

PCIe Gen 2: 2GB/s

PCIe Gen 1: 1GB/s

innodisk

2.9 Pin Assignment

Innodisk M.2 (P80) 4IE3 follows standard M.2 spec, socket 3 key M PCIe-based SSD pinout. See Table 10 for M.2 (P80) 4IE3 pin assignment.

Table 10: Innodisk M.2 (P80) 4IE3 Pin Assignment					
Signal Name	Pin #	Pin #	Signal Name		
		75	GND		
3.3V	74	73	GND		
3.3V	72	71	GND		
3.3V	70	69	NC		
NC	68	67	NC		
Notch	66	65	Notch		
Notch	64	63	Notch		
Notch	62	61	Notch		
Notch	60	59	Notch		
NC (Remark for MFG_CLOCK)	58	57	GND		
NC (Remark for MFG_DATA)	56	55	REFCLKp		
NC	54	53	REFCLKn		
CLKREQ# (I/O) (0V/1.8V/3.3V)	52	51	GND		
PERST# (I) (0V/1.8V/3.3V)	50	49	PERp0		
NC	48	47	PERn0		
NC	46	45	GND		
ALERT# (I) (0/1.8V)	44	43	PETp0		
SMB_DATA (I/O) (0/1.8V)	42	41	PETn0		
SMB_CLK (I/O) (0/1.8V)	40	39	GND		
NC	38	37	PERp1		
NC	36	35	PERn1		
NC	34	33	GND		
NC	32	31	PETp1		
NC	30	29	PETn1		
NC	28	27	GND		
NC	26	25	PERp2		
NC	24	23	PERn2		
NC	22	21	GND		
NC	20	19	PETp2		
3.3V	18	17	PETn2		
3.3V	16	15	GND		
3.3V	14	13	PERp3		

-			-	-
			is	
_		-		

M.2 (P80) 4IE3

3.3V	12	11	PERn3
LED1# (O) (OD)	10	9	GND
NC	8	7	PETp3
NC	6	5	PETn3
3.3V	4	3	GND
3.3V	2	1	GND



2.10 Mechanical Dimensions

M.2 Type 2280-D2-M

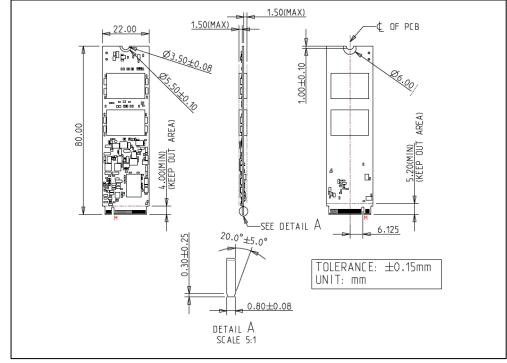


Figure 3: Innodisk M.2 (P80) 4IE3 mechanical drawing

M.2 Type 2280-D2-M with heatsink (Default accessory for WT)

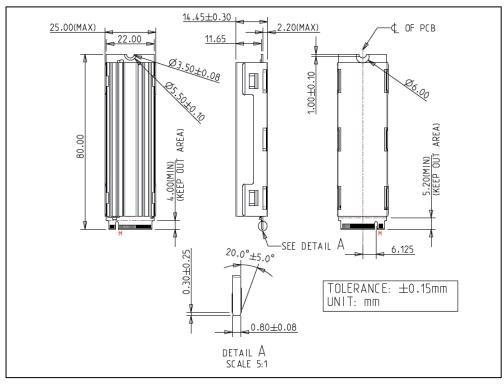


Figure 4: Innodisk M.2 (P80) 4IE3 with heatsink

Note: The appearance of silicone oil seeping out from the inside of the thermal pad is a normal occurrence.

Silicone oil is not electrically conductive, so it does not impact the functionality of SSD.

2.11 Assembly Weight

An Innodisk M.2 (P80) 4IE3 within NAND flash ICs, 640GB's weight is 7 grams approximately.

2.12 Seek Time

Innodisk M.2 (P80) 4IE3 is not of magnetic rotating design. There is no seek or rotational latency.

2.13 NAND Flash Memory

Innodisk M.2 (P80) 4IE3 uses industrial 3D TLC NAND flash memory, which is non-volatility, high reliability and high speed memory storage.



3. Theory of Operation

3.1 Overview

Figure 5 shows the operation of Innodisk M.2 (P80) 4IE3 from the system level, including the major hardware blocks.

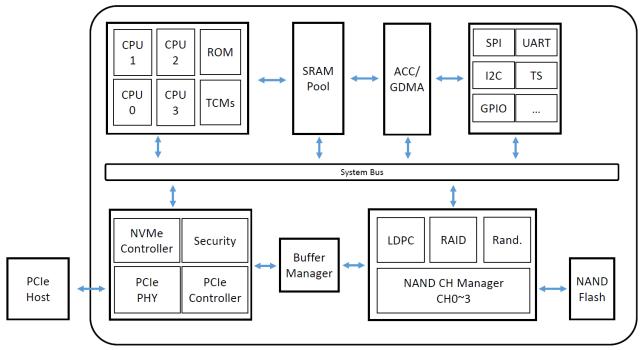


Figure 5: Innodisk M.2 (P80) 4IE3 Block Diagram

Innodisk M.2 (P80) 4IE3 integrates a PCIe Gen 4 x4 controller and NAND flash memories. Communication with the host occurs through the host interface, using the standard NVM Express protocol. Communication with the flash device(s) occurs through the flash interface.

3.2 PCIe Gen 4 x4 Controller

Innodisk M.2 (P80) 4IE3 is designed with innodisk ID309, a PCIe Gen 4 x4 controller which is compliant with NVMe 1.4, up to 64.0Gbps transfer speed. In addition, it is compliant with PCIe Gen 1, Gen 2 and Gen 3 specification. The controller supports up to four channels for flash interface.

3.3 Error Detection and Correction

Innodisk M.2 (P80) 4IE3 is designed with hardware LDPC ECC engine with hard-decision and soft-decision decoding. Low-density parity-check (LDPC) codes have excellent error correcting performance close to the Shannon limit when decoded with the belief-propagation (BP) algorithm using soft-decision information.

3.4 Wear-Leveling

Flash memory can be erased with a limited number of cycles. This number is called the **erase** *cycle limit* or *write endurance limit* and is defined by the flash NAND vendor. The erase cycle limit applies to each individual erase block in the flash device.

Innodisk M.2 (P80) 4IE3 uses a combination of two types of wear leveling- dynamic and static wear leveling- to distribute write cycling across an SSD and balance erase count of each block, thereby extending device lifetime.

3.5 Bad Blocks Management

Bad Blocks are blocks that contain one or more invalid bits whose reliability are not guaranteed. The Bad Blocks may be presented while the SSD is shipped, or may develop during the lifetime of the SSD. When a Bad Block is detected, it will be flagged as unusable block by firmware. The SSD implement Bad Blocks management that consists of Bad Blocks replacement and Error Correcting to avoid data error occurred. The functions will be enabled automatically to transfer data from Bad Blocks to spare blocks, and correct error bit.

3.6 Garbage Collection/TRIM

Garbage collection and TRIM technology are used to maintain data consistency and perform continual data cleansing on SSDs. It runs as a background process, freeing up valuable controller resources while sorting good data into available blocks, and deleting bad blocks. It also significantly reduces write operations to the drive, thereby increasing the SSD's speed and lifespan.

3.7 End to End Data Path Protection

End-to-end Data Path Protection that secures the data transmission between host system and NAND Flash. In the transmission path, no matter in or out, all buffer and storage implement Error Code Correction that optimizes the data integrity in the whole transmission of SSD.

3.8 Thermal Management

M.2 (P80) 4IE3 has built-in thermal sensor which can detect environment temperature of SSD. In the meantime, firmware will monitor the thermal sensor to prevent any failure of overheating. During extreme temperature, firmware will adjust the data transfer behavior to maintain the SSD's reliable operation.

3.9 iDataGuard

Innodisk's iData Guard is a comprehensive data protection mechanism that functions before and after a sudden power outage to the SSD. Low-power detection terminates data writing before an abnormal power-off, while table-remapping after power-on deletes corrupt data and maintains data integrity. Innodisk's iData Guard provides effective power cycling management, preventing data stored in flash from degrading with use.



3.10 Thermal Throttling

Thermal throttling is a protective mechanism designed to safeguard components from potential damage caused by excessive temperatures. When an SSD approaches a critical temperature threshold, Innodisk firmware activates the thermal throttling mechanism to regulate the SSD's temperature. Thermal throttling is crucial for SSDs since it prevents drive damage, which could otherwise result in data loss. However, it's worth noting that when thermal throttling is activated, read and write tasks may experience a reduction in speed.

3.11 TCG OPAL (Optional)

OPAL is a set of specifications for features of data storage devices that enhance security. These specifications are published by the Trusted Computing Group's Storage Work Group. Innodisk 4IE3 is compliant with TCG OPAL 2.0(*1). The capability of TCG OPAL Security mode allows multiple users with independent access control to read/write/erase independent data areas (LBA ranges). Each locking range adjusts by authenticated authority. Note that by default there is a single "Global Range" that encompasses the whole user data area. In TCG Opal Security Mode, Revert, Revert SP and GenKey command can erase all of data including global range and locking range; in the meantime generate the new encrypted key.

*1. You need to install TCG OPAL software to implement OPAL function, which is supplied by TCG OPAL software developed company



4. Installation Requirements

4.1 M.2 (P80) 4IE3 Pin Directions

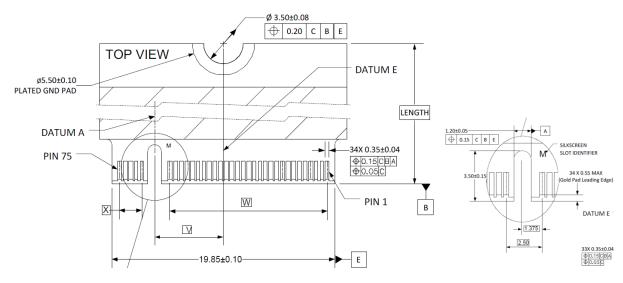


Figure 6: Signal Segment and Power Segment

4.2 Electrical Connections for M.2 (P80) 4IE3

M.2 interconnect is based on a 75 position Edge Card connector. The 75 position connector is intended to be keyed so as to distinguish between families of host interfaces and the various Sockets used in general Platforms. M.2 (P80) 4IE3 is compliant with M.2 Socket 3 key M.

4.3 Device Drive

M.2 (P80) 4IE3 is compliant with NVMe 1.4. Both Operation System and BIOS should include NVMe driver to compatible with NVMe device. Nowadays, most of OS includes NVMe in-box driver now. For more information about the driver support in each OS, please visit the website https://nvmexpress.org/drivers/. For BIOS NVMe driver support please contact with motherboard manufacturers.

5. SMART / Health Information

This log page is used to provide SMART and general health information. The information provided is over the life of the controller and is retained across power cycles. More details about Set Features command; please refer to NVM Express 1.4

5.1 Get Log Page (Log Identifier 02h)

Innodisk 4IE3 series SMART / Health Information Log are listed in following table.

Bytes	Descriptior	1								
	Critical Warning: This field indicates critical warnings for the state of the controller. Each bit corresponds to a critical warning type; multiple bits may be set to `1'. If a bit is cleared to `0', then that critical warning does not apply. Critical warnings may result in an asynchronous event notification to the host. Bits in this field represent the state at the time the Get Log Page command is processed and may not reflect the state at the time a related asynchronous event notification, if any, occurs or occurred.									
	Bit Definition									
	0	If set to `1', then the available spare capacity has fallen below the threshold.								
0	1	If set to `1', then a temperature is: a) greater than or equal to an over temperature threshold. b) less than or equal to an under temperature threshold.								
	2	If set to '1', then the NVM subsystem reliability has been degraded due to significant media related errors or any internal error that degrades NVM subsystem reliability.								
	3	If set to '1', then all of the media has been placed in read only mode. The controller shall not set this bit to '1' if the read-only condition on the media is a result of a change in the write protection state of a namespace.								
	4	If set to `1', then the volatile memory backup device has failed. This field is only valid if the controller has a volatile memory backup solution.								
	5	If set to `1', then the Persistent Memory Region has become read-only or unreliable.								
	7:6 Reserved									

Table 11: Get Log Page – SMART / Health Information Log

innod	isk	M.2 (P80) 4IE3											
	Composite Temperature: Contains a value corresponding to a temperature in degrees Kelvin that represents the current composite temperature of the controller and namespace(s)												
1:2	associated with that controller. The manner in which this value is computed is implementation specific and may not represent the actual temperature of any physical point in the NVM subsystem. The value of this field may be used to trigger an asynchronous event.												
	Warning and critical overheating composite temperature threshold values are reported by the WCTEMP and CCTEMP fields in the Identify Controller data structure.												
3	Available S capacity avai	pare: Contains a normalized percentage (0 to 100%) of the remaining spare lable.											
4	Available Spare Threshold: When the Available Spare falls below the threshold indicated in this field, an asynchronous event completion may occur. The value is indicated as a normalized percentage (0 to 100%). The values 101 to 255 are reserved.												
5	Percentage (see Teero): The table for the Lee tee tee tee tee tee tee tee tee te												
	 Endurance Group Critical Warning Summary: This field indicates critical warnings for the state of Endurance Groups. Each bit corresponds to a critical warning type, multiple bits may be set to '1'. If a bit is cleared to '0', then that critical warning does not apply to any Endurance Group. Critical warnings may result in an asynchronous event notification to the host. Bits in this field represent the current associated state and are not persistent. If a bit is set to '1' in one or more Endurance Groups, then the corresponding bit shall be set to '1' in this field. 												
	Bit	Definition											
6	0	If set to `1', then the available spare capacity of one or more Endurance Groups has fallen below the threshold.											
	1	Reserved											
	2	If set to '1', then the reliability of one or more Endurance Groups has been degraded due to significant media related errors or any internal error that degrades NVM subsystem reliability.											
	3	If set to '1', then the namespaces in one or more Endurance Groups have been placed in read only mode not as a result of a change in the write protection state of a namespace.											
1													

7:31	Reserved
32:47	Data Units Read: Contains the number of 512 byte data units the host has read from the controller as part of processing a SMART Data Units Read Command; this value does not include metadata. This value is reported in thousands (i.e., a value of 1 corresponds to 1,000 units of 512 bytes read) and is rounded up (e.g., one indicates that the number of 512 byte data units read is from 1 to 1,000, three indicates that the number of 512 byte data units read is from 2,001 to 3,000). Refer to the specific I/O Command Set specification for the list of SMART Data Units Read Commands that affect this field.
	A value of 0h in this field indicates that the number of SMART Data Units Read is not reported.
48:63	Data Units Written: Contains the number of 512 byte data units the host has written to the controller as part of processing a User Data Out Command; this value does not include metadata. This value is reported in thousands (i.e., a value of 1 corresponds to 1,000 units of 512 bytes written) and is rounded up (e.g., one indicates that the number of 512 byte data units written is from 1 to 1,000, three indicates that the number of 512 byte data units written is from 2,001 to 3,000). Refer to the specific I/O Command Set specification for the list of User Data Out Commands that affect this field. A value of 0h in this field indicates that the number of Data Units Written is not reported.
	Host Read Commands: Contains the number of SMART Host Read Commands completed by
64:79	the controller. Refer to the specific I/O Command Set specification for the list of SMART Host Read Commands that affect this field.
	Host Write Commands: Contains the number of User Data Out Commands completed by the
80:95	controller. Refer to the specific I/O Command Set specification for the list of User Data Out Commands that affect this field.
96:111	Controller Busy Time: Contains the amount of time the controller is busy with I/O commands. The controller is busy when there is a command outstanding to an I/O Queue (specifically, a command was issued via an I/O Submission Queue Tail doorbell write and the corresponding completion queue entry has not been posted yet to the associated I/O Completion Queue). This value is reported in minutes.
112:127	Power Cycles: Contains the number of power cycles.
128:143	Power On Hours: Contains the number of power-on hours. This may not include time that the controller was powered and in a non-operational power state.
144:159	Unsafe Shutdowns: Contains the number of unsafe shutdowns. This count is incremented when the controller does not report it is safe to power down prior to loss of main power.

innodi	sk M.2 (P80) 4IE3											
	Media and Data Integrity Errors: Contains the number of occurrences where the controller											
160:175	detected an unrecovered data integrity error. Errors such as uncorrectable ECC, CRC checksum											
	failure, or LBA tag mismatch are included in this field. Errors introduced as a result of a Write											
	Uncorrectable command (refer to the NVM Command Set Specification) may or may not be											
	included in this field.											
176:191	Number of Error Information Log Entries: Contains the number of Error Information log											
170.191	entries over the life of the controller.											
	Warning Composite Temperature Time: Contains the amount of time in minutes that the											
	controller is operational and the Composite Temperature is greater than or equal to the Warning											
192:195	Composite Temperature Threshold (WCTEMP) field and less than the Critical Composite											
192.195	Temperature Threshold (CCTEMP) field in the Identify Controller data structure in Figure 275.											
	If the value of the WCTEMP or CCTEMP field is 0h, then this field is always cleared to 0h											
	regardless of the Composite Temperature value.											
	Critical Composite Temperature Time: Contains the amount of time in minutes that the											
	controller is operational and the Composite Temperature is greater than or equal to the Critical											
196:199	Composite Temperature Threshold (CCTEMP) field in the Identify Controller data structure.											
	If the value of the CCTEMP field is 0h, then this field is always cleared to 0h regardless of the											
	Composite Temperature value.											
200:201	Temperature Sensor 1: Contains the current temperature reported by the embedded thermal											
200.201	sensor in the controller.											
202:203	Temperature Sensor 2: Contains the current temperature reported by the embedded thermal											
202.205	sensor in the NAND Flash (Channel #0 and CE #0).											
204:205	Temperature Sensor 3: Contains the current temperature reported by the embedded thermal											
201.205	sensor in the NAND Flash (Channel #0 and CE #0).											
206:207	Temperature Sensor 4: Contains the current temperature reported by the embedded thermal											
200.207	sensor in the NAND Flash (Last channel and CE #0).											
208:209	Temperature Sensor 5: Contains the current temperature reported by temperature sensor 5.											
210:211	Temperature Sensor 6: Contains the current temperature reported by temperature sensor 6.											
212:213	Temperature Sensor 7: Contains the current temperature reported by temperature sensor 7.											
214:215	Temperature Sensor 8: Contains the current temperature reported by temperature sensor 8.											
	Thermal Management Temperature 1 Transition Count: Contains the number of times the											
216:219	controller transitioned to lower power active power states or performed vendor specific thermal											
210.219	management actions while minimizing the impact on performance in order to attempt to reduce											
	the Composite Temperature because of the host controlled thermal management feature.											
	Thermal Management Temperature 2 Transition Count: Contains the number of times the											
	controller transitioned to lower power active power states or performed vendor specific thermal											
220:223	management actions regardless of the impact on performance (e.g., heavy throttling) in order											
	to attempt to reduce the Composite Temperature because of the host controlled thermal											
	management feature.											

innodi	SK M.2 (P80) 4IE3								
	Total Time For Thermal Management Temperature 1: Contains the number of seconds that								
	the controller had transitioned to lower power active power states or performed vendor specific								
224:227	thermal management actions while minimizing the impact on performance in order to attempt to								
	reduce the Composite Temperature because of the host controlled thermal management								
	feature.								
	Total Time For Thermal Management Temperature 2: Contains the number of seconds that								
	the controller had transitioned to lower power active power states or performed vendor specific								
228:231	thermal management actions regardless of the impact on performance (e.g., heavy throttling)								
	in order to attempt to reduce the Composite Temperature because of the host controlled thermal								
	management feature.								
232:337	Reserved								
338:345	Later Bad Count								
346:353	Power-On hours Count								
354:361	Drive Power Cycle Count								
362:369	Total Bad Block Count								
370:377	User Max Erase Count								
378:385	User Avg Erase Count								
386:393	Device Life								
394:401	Spare Block Count								
402:409	Program Fail Count								
410:417	Erase Fail Count								
418:425	Unexpected Power Loss Count								
426:433	Temperature (Kelvin - K °K)								
434:441	Flash ID								
442:449	Later Bad Block Info (Read / Write / Erase)								
450:457	Total LBAs Written (unit = 32MB)								
458:465	Total LBAs Read (unit = 32MB)								



6. Part Number Rule

CODE	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	
	D	н	м	2	8	-	Α	6	0	D	н	1	к	С	Α	Q	F	(H)	-	x	x	
Def											on											
Code 1 st (Disk)										Code 14 th (Operation Temperature)												
D : Disk	D : Disk										C: Standard Grade (0°C~ +70°C)											
	Со	de 2	nd (F	eatu	ure s	set)			•	W: Industrial Grade (-40°C~ +85°C)												
H : iSLC se	ries																					
	Code	3 rd	~5 th	(Fo	r <mark>m f</mark> a	acto	r)								(Int	erna	l co	ntrol)				
M28: M.2 T	ype 2	2280	-D2-	Μ						A∼Z:	BGA	PCB	vers	sion.								
			•																_			
		le 7 ^t	^հ ~9	th (C	apa	city)				Code 16 th (Channel of data transfer)												
40G: 40GB										D: Dual Channels												
80G: 80GB									(Q: Quad Channels												
A60: 160G																						
D2G: 320G																						
F4G: 640G	В																					
					_		_		_								_		_			
	Code			2 ^m (0	Cont	rolle	er)			Code 17 th (Flash Type)												
DH1: PCIe							<u> </u>			F: Kioxia 3D TLC												
DH2: PCIe	41E3	serie	es wi		_G ()	PAL	runct	lon														
	C		oth /		.	a a b						C	4. 1	oth /	0~+:		Erre	ation	•			
K. 112 Jay	Code 13 th (Flash mode)									Code 18 th (Optional Function)												
,										H: with heatsink accessory (WT default)												
										W: H/W Write Protect Function Code 20 th ~21 st (Customize code)												
									-			e	20		- ('	cust	51112		-e)			